

DETAILS OF THE CONDUCTIVE**General :**

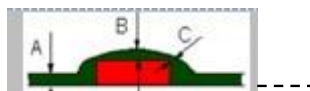
Minimum conductor width (inner and outer) : 0.120 mm
 Minimum spacing between conductors (i and o) : 0.120 mm

DIMENSIONS OF VIAS*Plated through via's:*

Designed hole diameter : 0.200 mm
 Tolerance on finished hole diameter : none
 Copper land diameter : 0.400 mm
 Minimum copper thickness into plated through via's : 0.015 mm

PCB STRUCTURE

Number of layers : 4
 Total thickness min : 1.584 mm
 Copper 1 final thickness0.042 mm (0.017mm Cu + Plating)
 Epoxy 1 basis thickness (core)0.150 mm
 Copper 2 final thickness0.017 mm
 Epoxy 2 basis thickness (core)1.160 mm
 Copper 3 final thickness0.017 mm
 Epoxy 3 basis thickness (core)0.150 mm
 Copper 4 final thickness0.042 mm (0.017mm Cu + Plating)

SOLDER RESIST SPECIFICATION

(Copper : Red – Solder Resist : Green)

Thickness A : NA
 Thickness B : NA
 Thickness C : NA

FINISHING

Ni + Au, thickness 5 +4/-2µm electroless Ni and 0.1 +0.05/-0.05 µm immersion Au

MATERIAL

Dielectric permittivity: 4.3
 Solder resist permittivity: 3.4
 All material MUST be compatible with Lead Free process and compatible with ROHS directive.

IMPEDANCES REQUIREMENTS:**Single-ended**

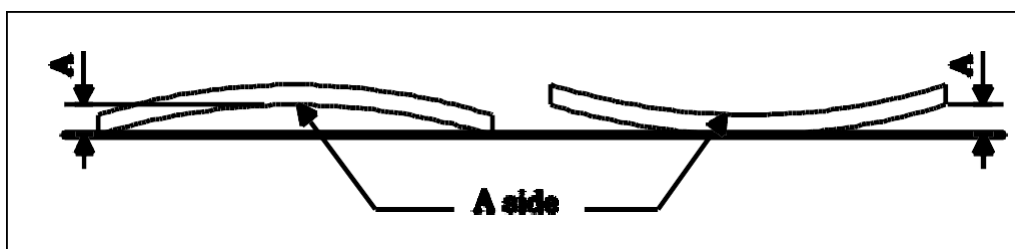
Layer	Track width	Distance between diff tracks	Isolation to gnd	Impedance Requested	Reference
Layer 1 (RF)	560um	-	120um	50 Ohms	Layer 3
Layer 1 (RF)	260um	-	310um	50 Ohms	Layer 2

STRATEGIC PADS AND TRACKS:

N/A

BOW (before and after reflow)

Acceptable bending => A under or equal : 1.5 mm



TWIST (before and after reflow)

Acceptable twist is lower or equal : 1.5 mm

BOW + TWIST(before and after reflow)

Accept. bow + twist sum is lower or equal : 1.5 mm